



US006143636A

United States Patent [19]

[11] Patent Number: **6,143,636**

Forbes et al.

[45] Date of Patent: ***Nov. 7, 2000**

[54] **HIGH DENSITY FLASH MEMORY**

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(List continued on next page.)

[73] Assignee: **Micron Technology, Inc.**, Boise, Id.

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[*] Notice: This patent is subject to a terminal disclaimer.

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[21] Appl. No.: **09/137,328**

[22] Filed: **Aug. 20, 1998**

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Related U.S. Application Data

[62] Division of application No. 08/889,553, Jul. 8, 1997.

[51] **Int. Cl.**⁷ **H01L 21/3205**; H01L 21/4763

[52] **U.S. Cl.** **438/587**; 438/259; 438/212;
438/268; 257/315; 257/319

[58] **Field of Search** 438/259, 257,
438/587; 257/319

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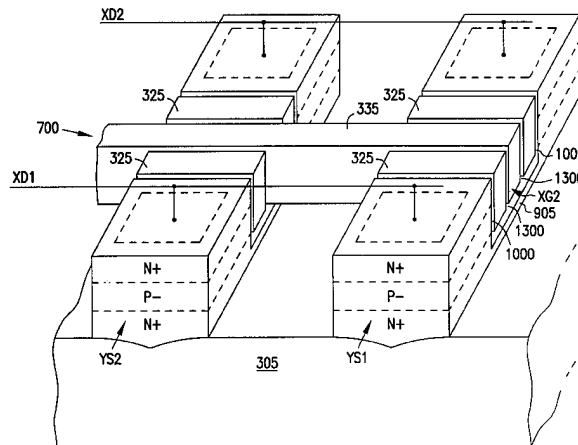
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[57] ABSTRACT

A high density flash EEPROM provides increased nonvolatile storage capacity. A memory cell array includes densely packed memory cells, each cell having a semiconductor pillar providing shared source/drain regions for two vertical floating gate transistors that have individual floating and control gates distributed on opposing sides of the pillar. The control gates are formed together with interconnecting gate lines. First source/drain terminals are row addressable by interconnection lines disposed substantially orthogonal to the gate lines. Second source/drain terminals are column addressable by data lines disposed substantially parallel to the gate lines. Both bulk semiconductor and silicon-on-insulator embodiments are provided. If a floating gate transistor is used to store a single bit of data, an area of only $2F^2$ is needed per bit of data, where F is the minimum lithographic feature size. If multiple charge states (more than two) are used, an area of less than $2F^2$ is needed per bit of data.

14 Claims, 14 Drawing Sheets



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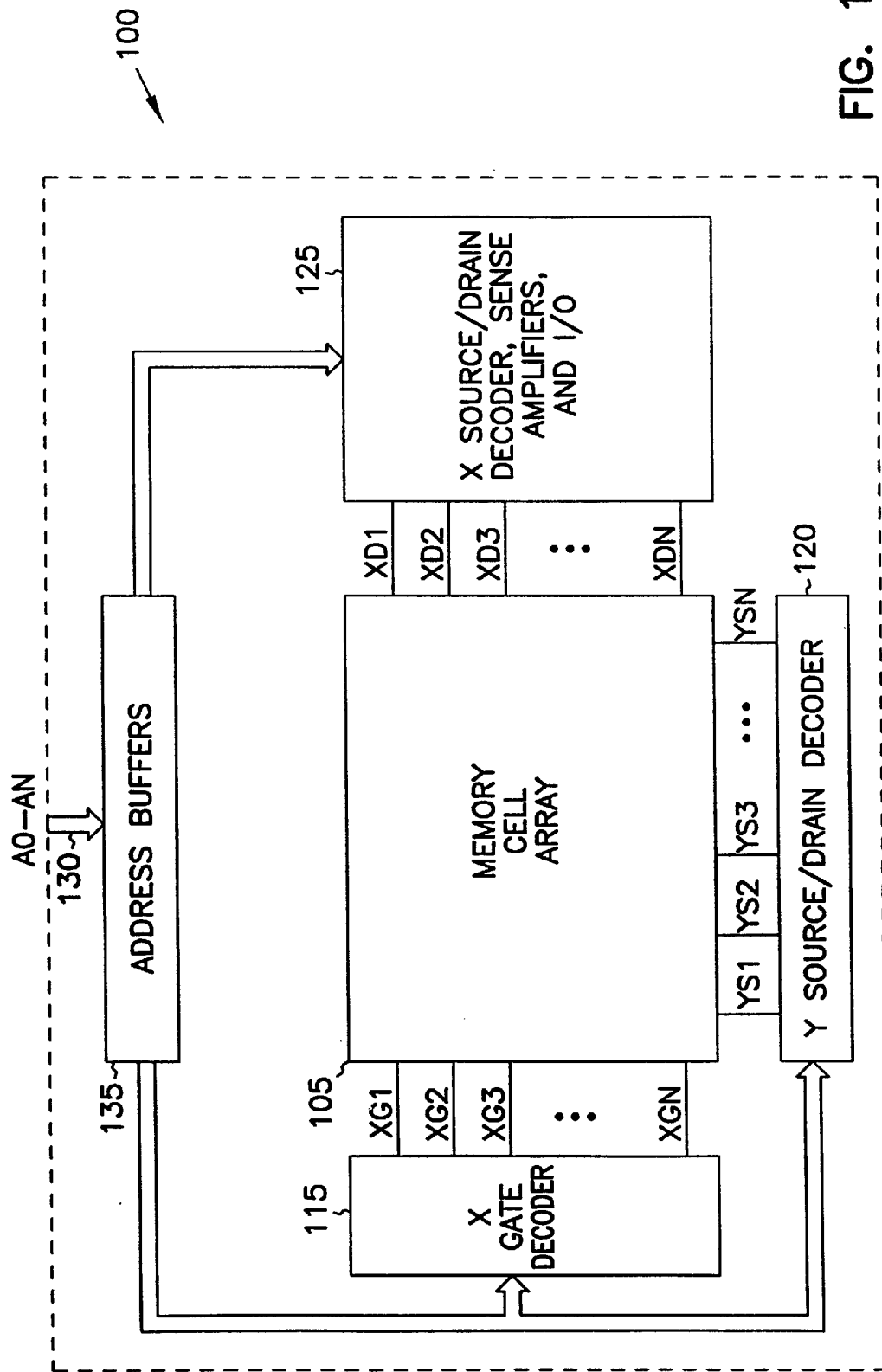


FIG. 1

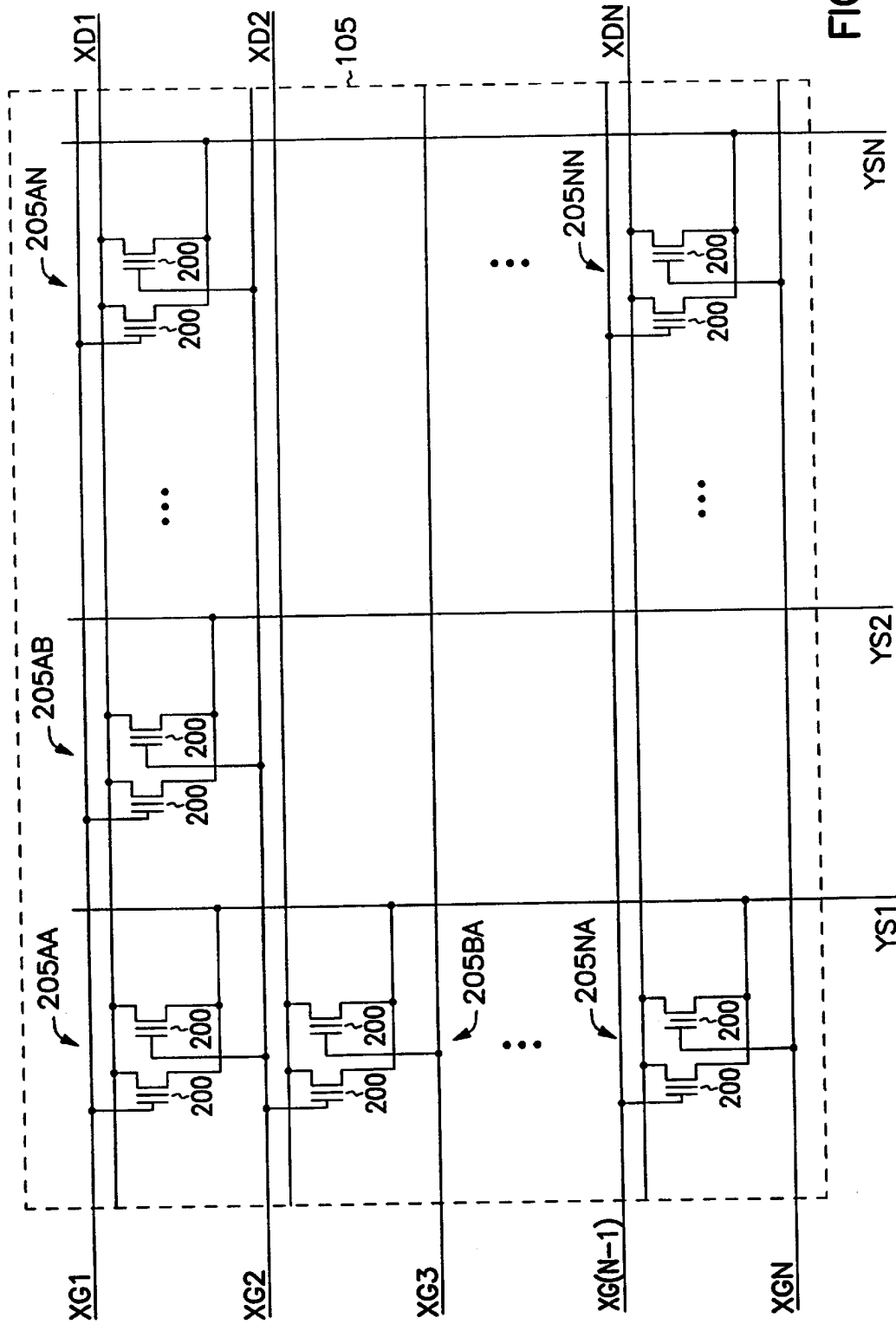


FIG. 2

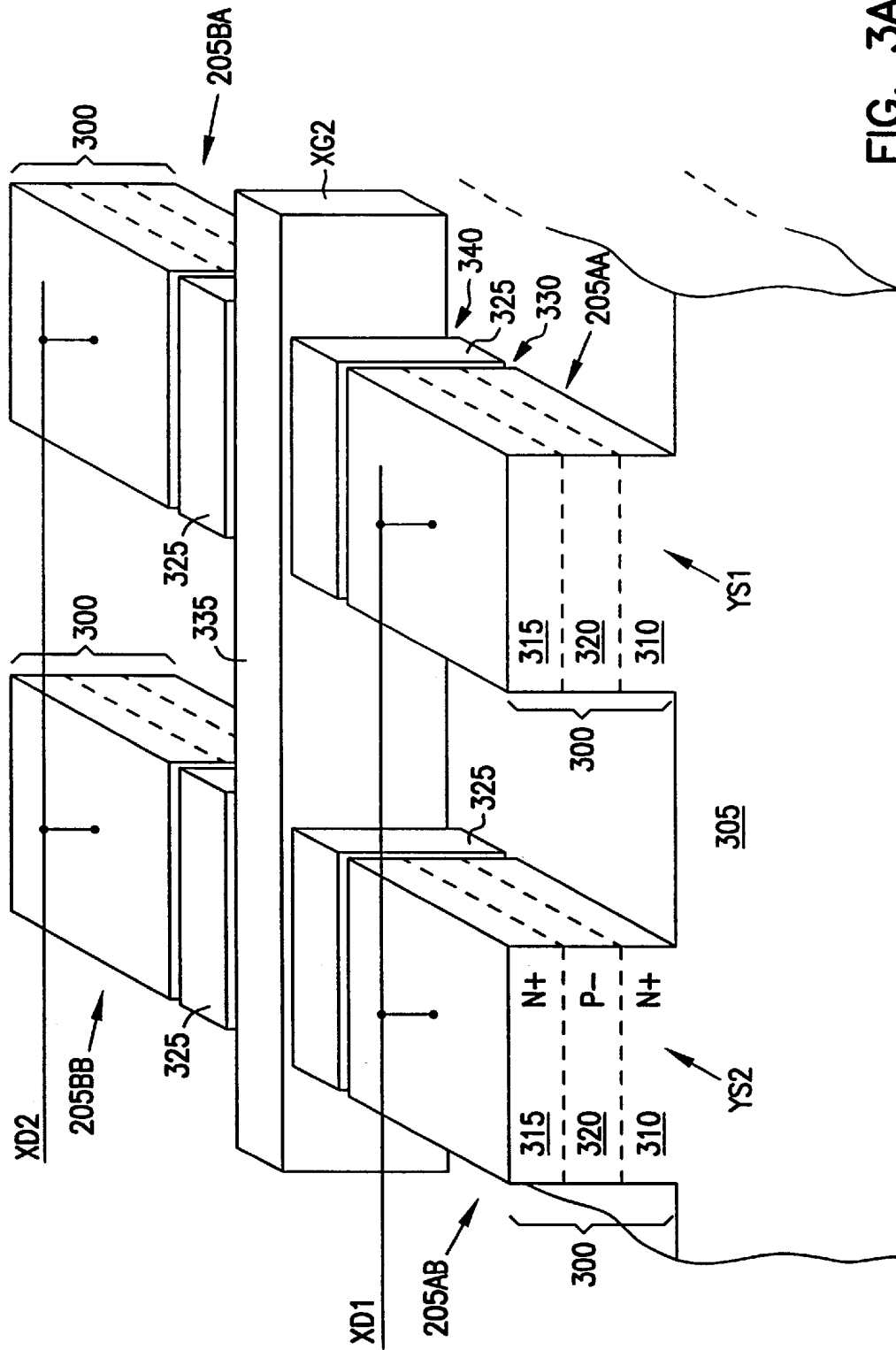


FIG. 3A

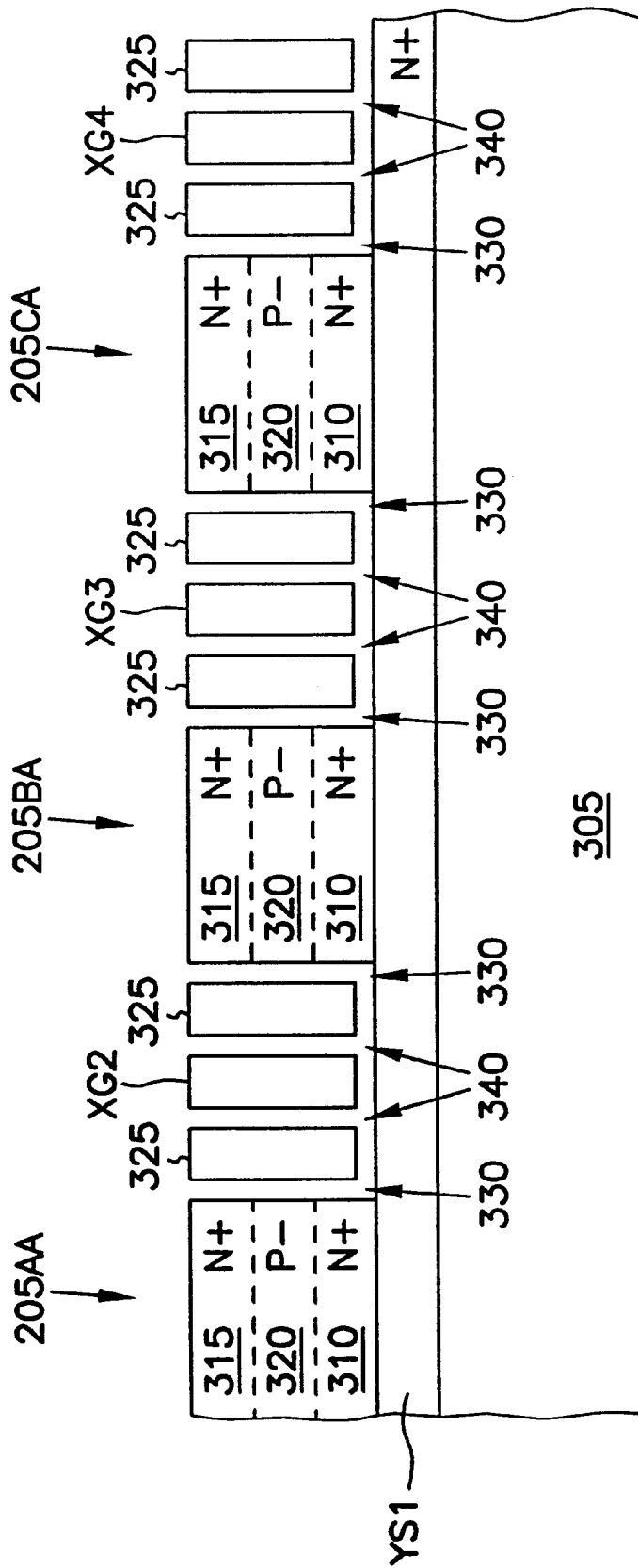


FIG. 3B

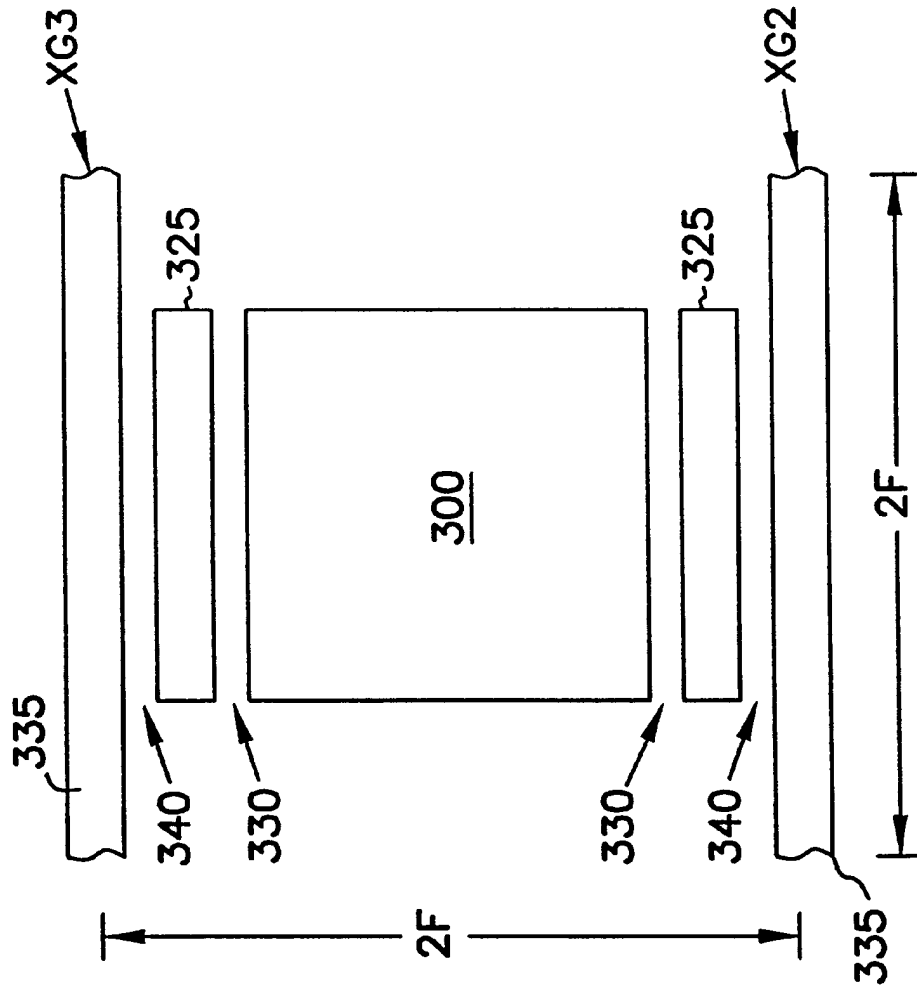


FIG. 4

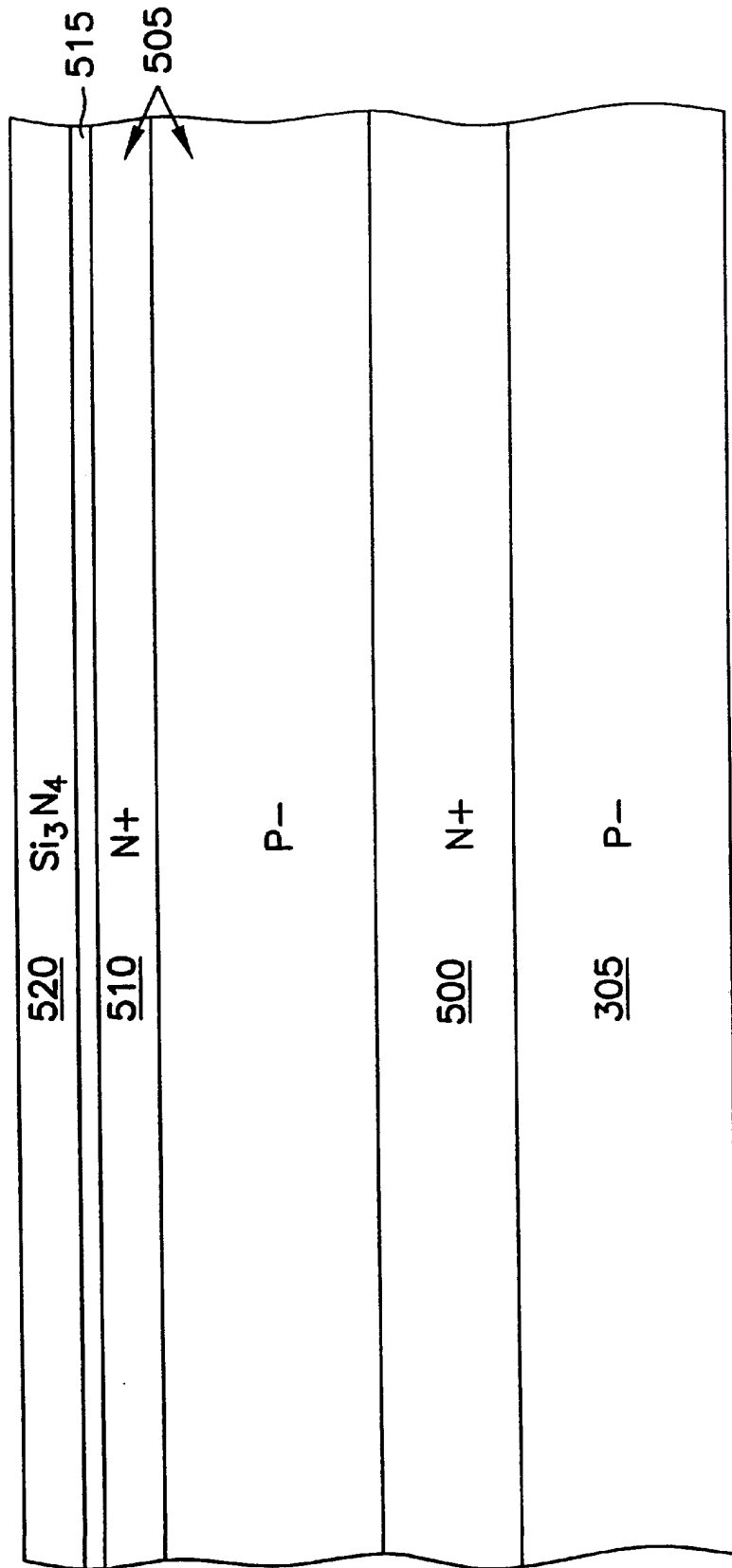


FIG. 5

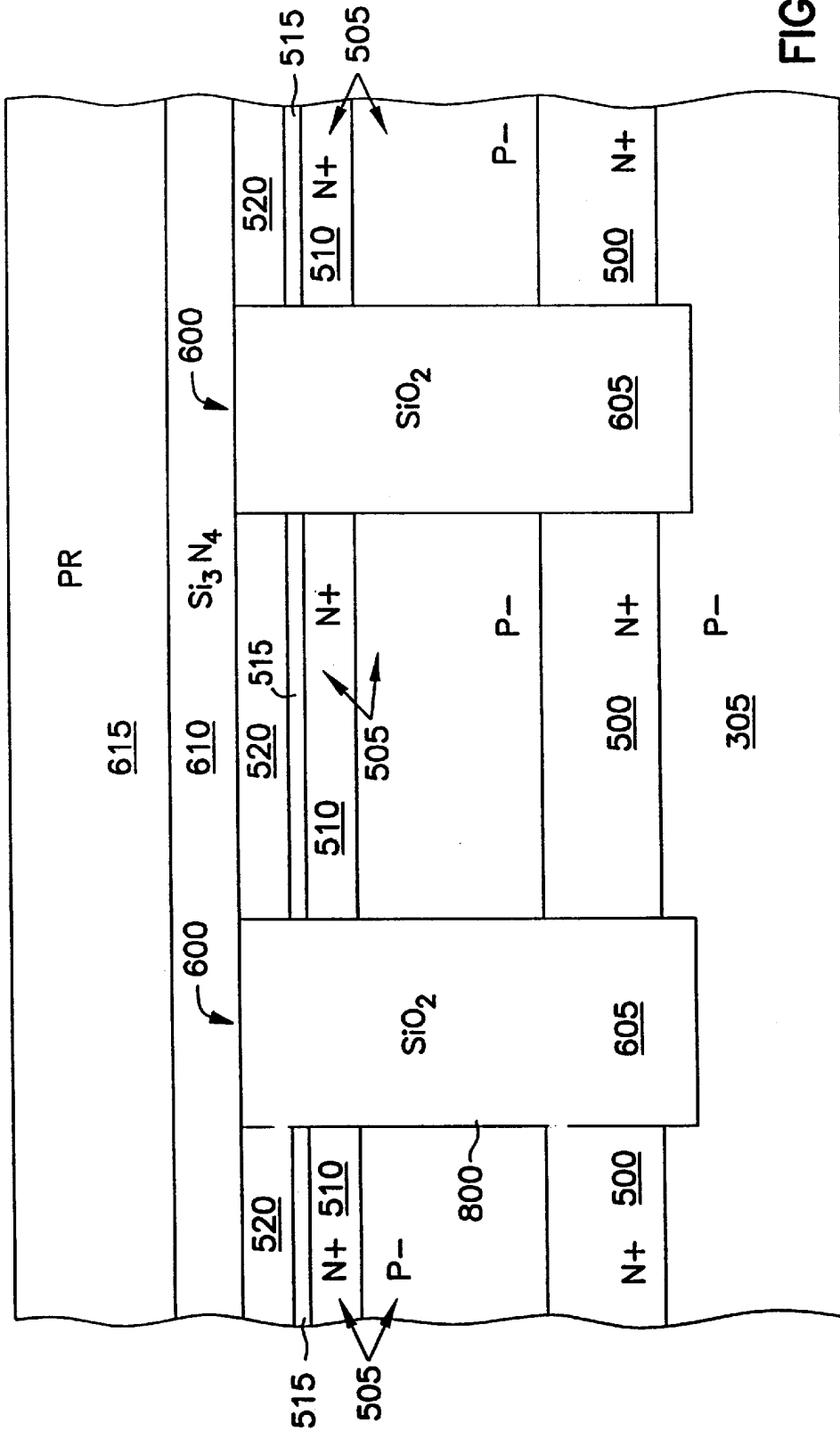


FIG. 6

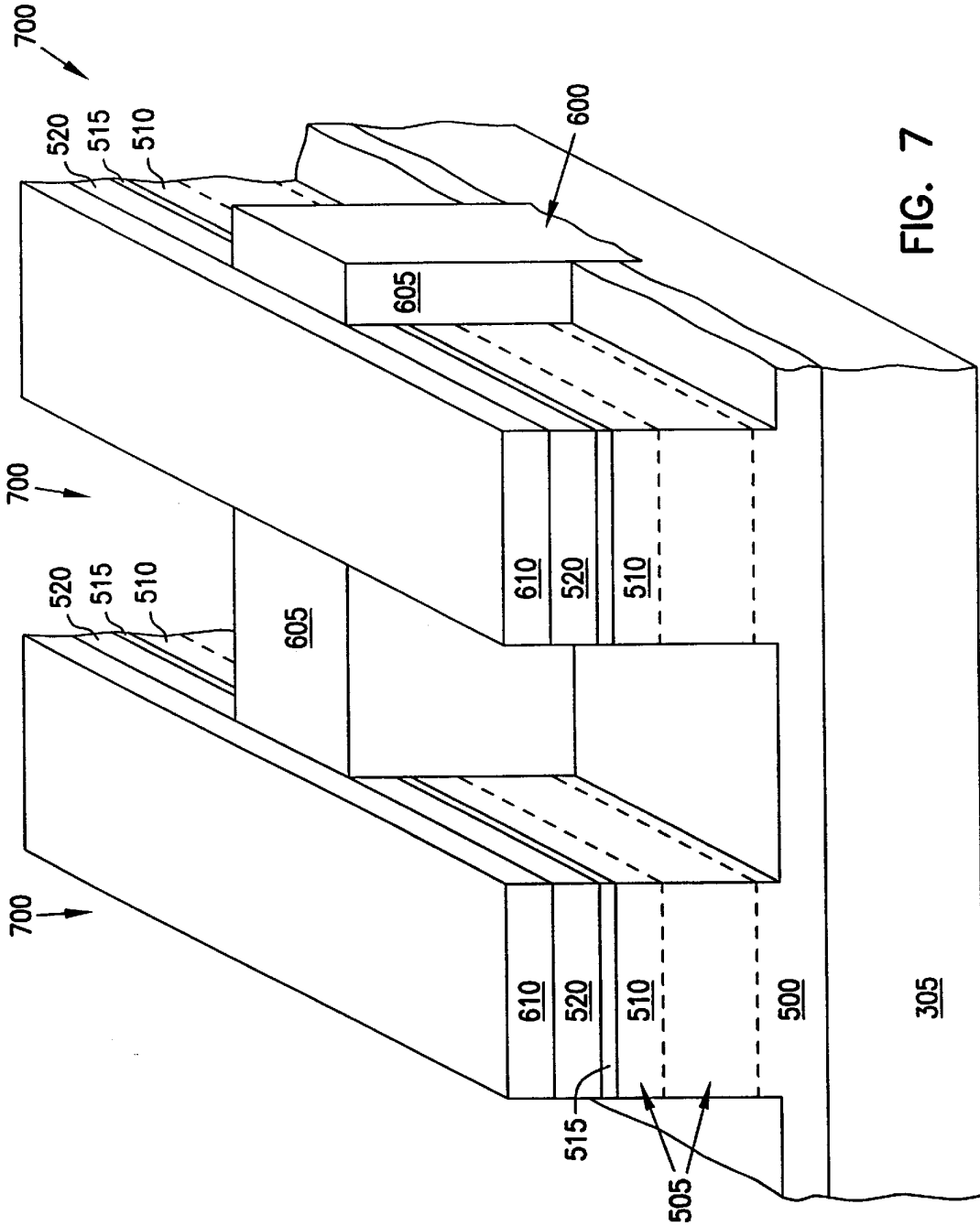


FIG. 7

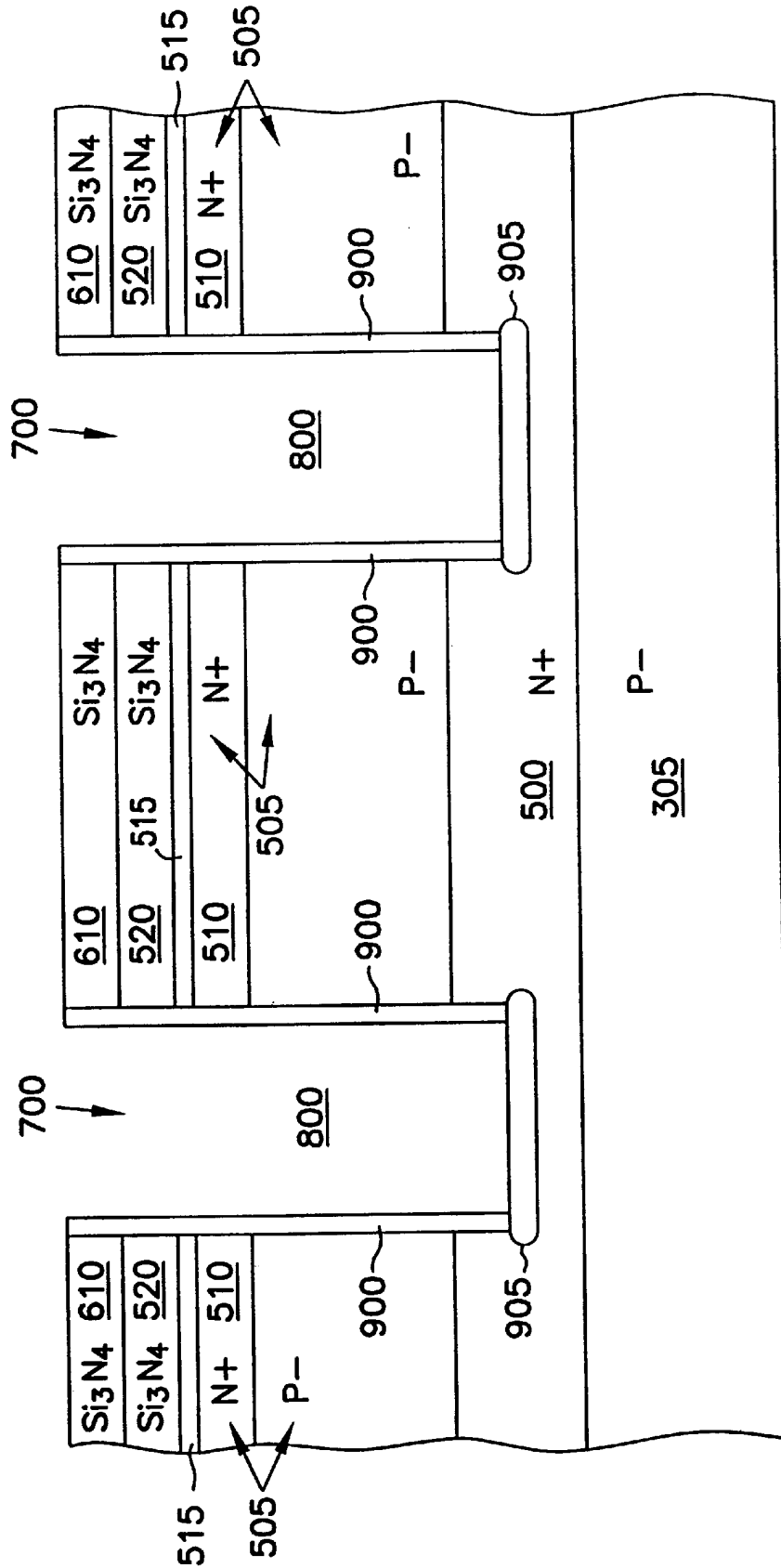


FIG. 9

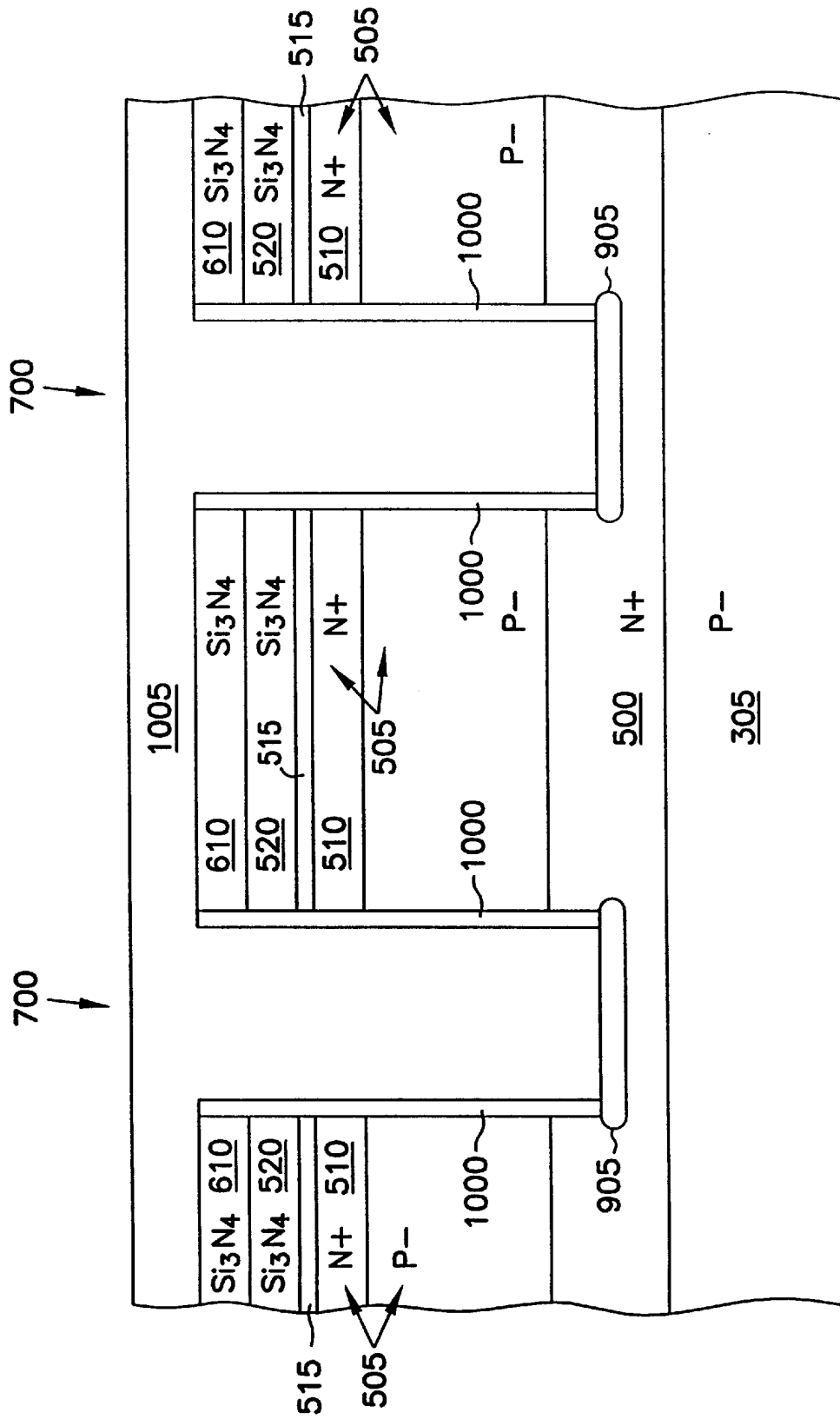


FIG. 10

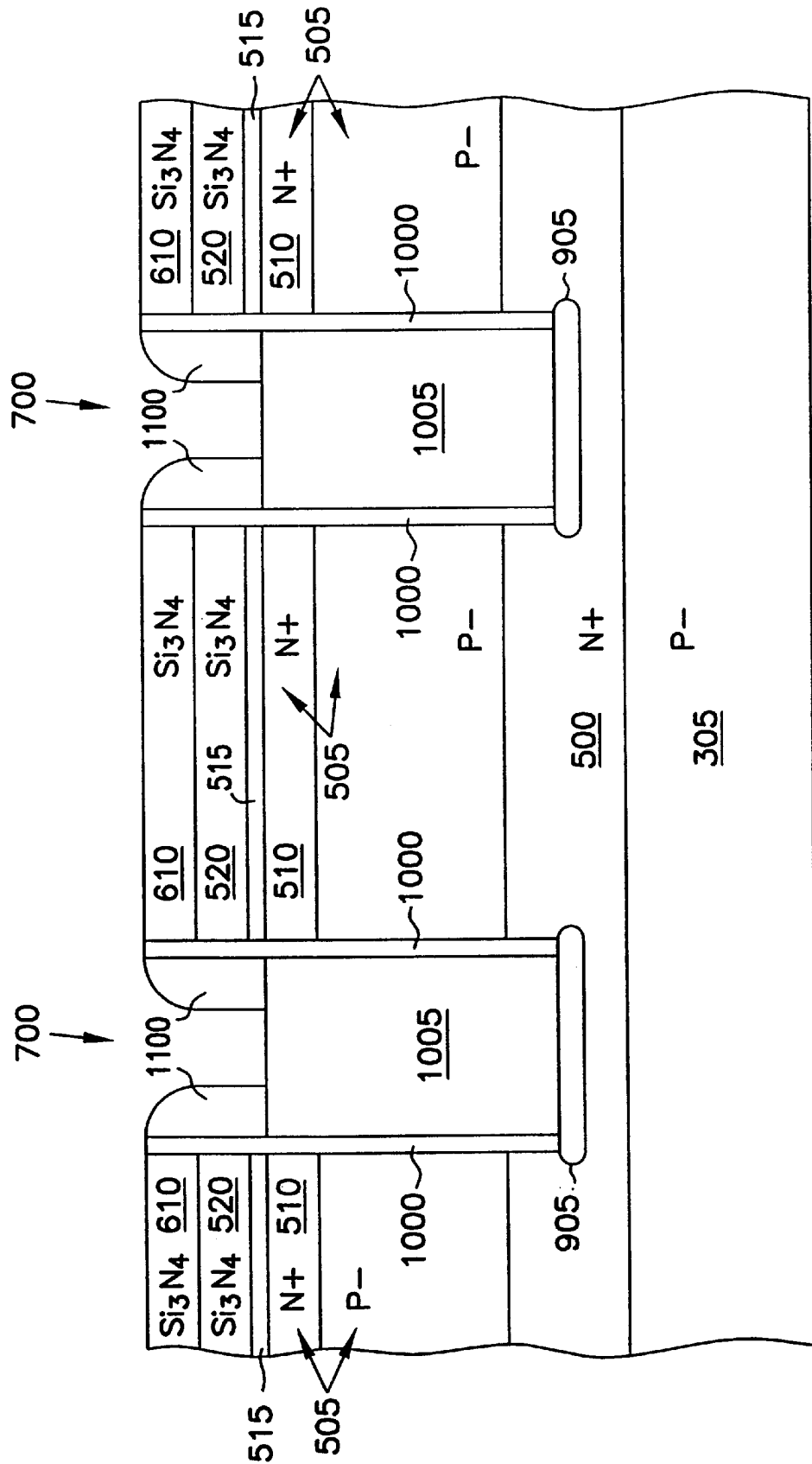


FIG. 11

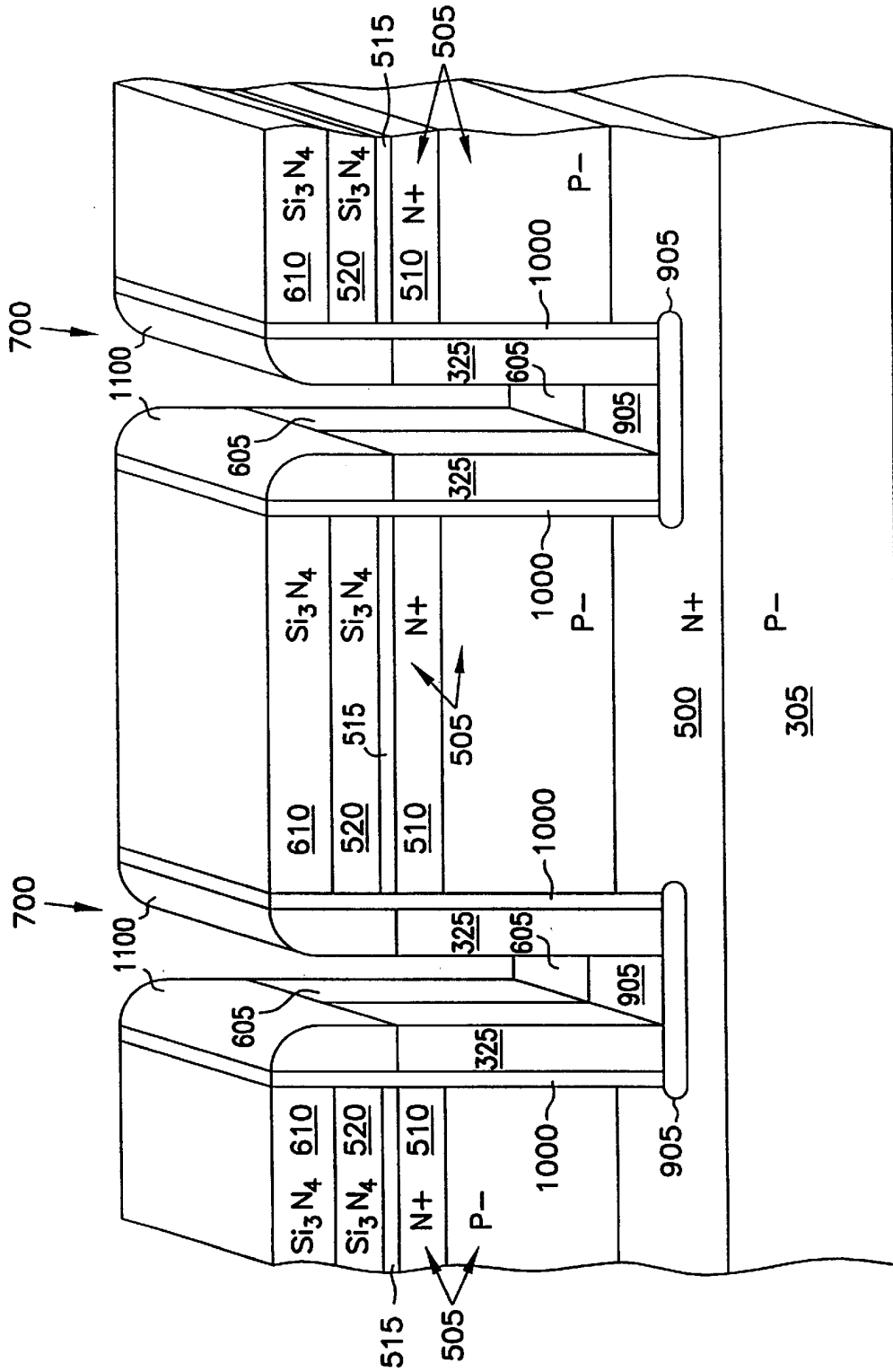


FIG. 12

HIGH DENSITY FLASH MEMORY**CROSS REFERENCE TO RELATED APPLICATIONS**

This application is a divisional of U.S. patent application Ser. No. 08/889,553, filed Jul. 8, 1997 (the '553 Application). The '553 Application is incorporated herein by reference.

This application is related to co-pending, commonly assigned patent application Ser. No. 08/889,554, filed on Jul. 8, 1997, which disclosure is herein incorporated by reference.

TECHNICAL FIELD OF THE INVENTION

This invention relates generally to integrated circuits, and particularly to floating gate transistor structures for use in nonvolatile semiconductor memories such as in flash EEPROM memory cells.

BACKGROUND OF THE INVENTION

Electrically erasable and programmable read only memories (EEPROMS) are reprogrammable nonvolatile memories that are widely used in computer systems for storing data both when power is supplied or removed. The typical data storage element of an EEPROM is a floating gate transistor, which is a field-effect transistor (FET) having an electrically isolated (floating) gate that controls electrical conduction between source and drain regions. Data is represented by charge stored on the floating gate and the resulting conductivity obtained between source and drain regions.

Increasing the storage capacity of EEPROM memories requires a reduction in the size of the floating gate transistors and other EEPROM components in order to increase the EEPROM's density. However, memory density is typically limited by a minimum lithographic feature size (F) that is imposed by lithographic processes used during fabrication. For example, the present generation of high density dynamic random access memories (DRAMs), which are capable of storing 256 Megabits of data, require an area of $8F^2$ per bit of data. There is a need in the art to provide even higher density memories in order to further increase storage capacity.

SUMMARY OF THE INVENTION

The present invention includes a high density electrically erasable and programmable read only memory (EEPROM) providing increased nonvolatile storage capacity. The memory allows simultaneous erasure of multiple data bits, and is referred to as flash EEPROM. Both bulk semiconductor and semiconductor-on-insulator embodiments are included.

In one embodiment of the invention, a memory cell includes a pillar of semiconductor material that extends outwardly from a working surface of a substrate. The pillar includes source/drain and body regions and has a number of sides. A number of floating gates are included in each memory cell, for example a pair of floating gates on opposing sides of the pillar. Each gate is associated with a side of the pillar. A number of control gates are also included in each memory cell. Each control gate is associated with a floating gate so as to allow selective storage and retrieval of data on the floating gates. In one embodiment, the control gate is capable of storing more than two charge states on its associated floating gate.

In another embodiment of the invention, a floating gate transistor is fabricated upon a substrate. The floating gate

transistor includes a first conductivity type semiconductor pillar. The pillar has top and side surfaces and is formed upon the substrate. A first source/drain region, of a second conductivity type, is formed proximal to an interface between the pillar and the substrate. A second source/drain region, of a second conductivity type, is formed in a portion of the pillar that is distal to the substrate and separate from the first source/drain region. A gate dielectric is formed on at least a portion of the side surface of the pillar. A floating gate is formed substantially adjacent to a portion of the side surface of the pillar and separated therefrom by the gate dielectric. A control gate is formed substantially adjacent to the floating gate and insulated therefrom. An intergate dielectric is formed, interposed between the floating and control gates.

In another embodiment of the invention, a memory cell is fabricated upon a substrate. The memory cell includes a first conductivity type semiconductor pillar. The pillar has top and side surfaces and is formed upon the substrate. A first source/drain region, of a second conductivity type, formed proximal to an interface between the pillar and the substrate. A second source/drain region, of a second conductivity type, is formed in a portion of the pillar that is distal to the substrate and separate from the first source/drain region. A gate dielectric is formed on at least a portion of the side surface of the pillar. A plurality of floating gates are formed, for example a pair of floating gates on opposing sides of the pillar. Each floating gate is substantially adjacent to a portion of the side surface of the pillar and separated therefrom by the gate dielectric. A plurality of control gates are formed, each of which is substantially adjacent to one of the floating gates and insulated therefrom. An intergate dielectric is formed, interposed between each of the substantially adjacent floating and control gates.

In another embodiment of the invention a nonvolatile memory array is fabricated upon a substrate. The memory array includes a plurality of memory cells, as described above. The memory array also includes a plurality of gate lines, e.g. substantially parallel in a first direction. Each gate line interconnects ones of the control gates in ones of the memory cells. At least one first source/drain interconnection line is formed, e.g. at least partially within the substrate. The first source/drain interconnection line interconnects ones of the first source/drain regions of ones of the memory cells. A plurality of data lines is formed. Each data line interconnects ones of the second source/drain regions of ones of the memory cells.

In another embodiment, the present invention provides a method of forming a memory array. The method includes several steps, as described below. A plurality of first conductivity type semiconductor pillars are formed upon a substrate. Each pillar has top and side surfaces. A plurality of first source/drain regions, of a second conductivity type, are formed. Each of the first source/drain regions is formed proximately to an interface between the pillar and the substrate. A plurality of second source/drain regions, of a second conductivity type, is formed. Each of the second source/drain regions is formed within one of the pillars and distal to the substrate and separate from the first source drain region. A gate dielectric is formed on at least a portion of the side surfaces of the pillars. A plurality of floating gates is formed. Each of the floating gates is formed substantially adjacent to a portion of the side surface of one of the pillars and separated therefrom by the gate dielectric. A plurality of control gates is formed. Each of the control gates is formed substantially adjacent to one of the floating gates and insulated therefrom. An intergate dielectric is formed, inter-

posed between ones of the floating gates and ones of the control gates. A plurality of gate lines is formed. Each gate line interconnects ones of the control gates. At least one first source/drain interconnection line is formed, e.g. at least partially within the substrate. The first source/drain interconnection line interconnects ones of the first source/drain regions. A plurality of data lines is formed. Each data line interconnects ones of the second/source drain regions.

In one embodiment, the method of forming a memory array on a substrate includes forming a first source/drain layer at a surface of the substrate. A semiconductor epitaxial layer is formed on the first source/drain layer. A second source/drain layer is formed at a surface of the epitaxial layer. A plurality of substantially parallel first troughs are etched, in a first direction, in the epitaxial layer. The first troughs are filled with an insulator. A plurality of substantially parallel second troughs are etched in the epitaxial layer, in a second direction that is substantially orthogonal to the first direction. A gate dielectric layer is formed substantially adjacent to sidewall regions of the second troughs. A conductive layer is formed in the second troughs. A portion of the conductive layer in the second troughs is removed, such that floating gate regions are formed along the sidewall regions therein and separated from the sidewall regions by the gate dielectric layer. An intergate dielectric layer is formed on exposed portions of the floating gate regions in the second troughs. Control gate regions and gate lines are formed between opposing floating gate regions in the second troughs and separated from the floating gate regions in the second troughs by the intergate dielectric layer.

Thus, bulk semiconductor and semiconductor-on-insulator embodiments of the present invention provide a high density flash EEPROM having increased nonvolatile storage capacity. If a floating gate transistor is used to store a single bit of data, an area of only $2F^2$ is needed per bit of data, where F is the minimum lithographic feature size. If multiple charge states (more than two) are used, an area of less than $2F^2$ is needed per bit of data. The increased storage capacity of the flash EEPROM is particularly advantageous in replacing hard disk drive data storage in computer systems. In such an application, the delicate mechanical components included in the hard disk drive are replaced by rugged, small, and durable solid-state flash EEPROM packages. The flash EEPROMs provide improved performance, extended rewrite cycles, increased reliability, lower power consumption, and improved portability.

BRIEF DESCRIPTION OF THE DRAWINGS

In the drawings, like numerals describe substantially similar components throughout the several views.

FIG. 1 is a schematic/block diagram illustrating generally an architecture of one embodiment of a nonvolatile memory, according to the teachings of the invention, including an array having a plurality of memory cells.

FIG. 2 is a schematic diagram illustrating generally one embodiment of an array of memory cells according to the teachings of the invention.

FIG. 3A is a perspective view illustrating generally one embodiment of a portion of an array of memory cells according to the teachings of the invention.

FIG. 3B is a cross-sectional view illustrating generally one embodiment of the invention.

FIG. 4 is a plan view from above of a working surface of a substrate, which illustrates one embodiment of one of a memory cell according to the teachings of the invention.

FIGS. 5-13 illustrate generally various stages of one embodiment of a method of forming an array of memory cells according to the teachings of the invention.

DETAILED DESCRIPTION OF THE INVENTION

In the following detailed description, reference is made to the accompanying drawings which form a part hereof, and in which is shown by way of illustration specific embodiments in which the invention may be practiced. These embodiments are described in sufficient detail to enable those skilled in the art to practice the invention, and it is to be understood that the embodiments may be combined, or that other embodiments may be utilized and that structural, logical and electrical changes may be made without departing from the scope of the present invention. In the following description, the terms wafer and substrate are interchangeably used to refer generally to any structure on which integrated circuits are formed, and also to such structures during various stages of integrated circuit fabrication. Both terms include doped and undoped semiconductors, epitaxial layers of a semiconductor on a supporting semiconductor or insulating material, combinations of such layers, as well as other such structures that are known in the art, including bulk semiconductor and semiconductor-on-insulator (SOI) substrates. In the drawings, like numerals describe substantially similar components throughout the several views. The following detailed description is not to be taken in a limiting sense.

FIG. 1 is a schematic/block diagram illustrating generally an architecture of one embodiment of a memory **100** according to the present invention. In the embodiment of FIG. 1, memory **100** is a nonvolatile high density electrically erasable and programmable read only memory (EEPROM allowing simultaneous erasure of multiple data bits, referred to as flash EEPROM. However, the invention can be applied to other semiconductor memory devices, such as static or dynamic random access memories (SRAMs and DRAMs, respectively), synchronous random access memories or other types of memories that include a matrix of selectively addressable memory cells.

Memory **100** includes a memory cell array **105**, having memory cells therein that include floating gate transistors, as described below. X gate decoder **115** provides a plurality of gate lines, XG1, XG2, . . . , XGN for addressing floating gate transistors in array **105**, as described below. Y source/drain decoder **120** provides a plurality of first source/drain interconnection lines YS1, YS2, . . . , YSN, for accessing first source/drain regions of the floating gate transistors in array **105**, as described below. In an embodiment in which commonly connected first source/drain interconnection lines YS1, YS2, . . . , YSN are used, Y source/drain decoder **120** may be omitted. X source/drain decoder **125** provides a plurality of data lines, XD1, XD2, . . . , XDN for accessing second source/drain regions of the floating gate transistors in array **105**, as described below. X source/drain decoder **125** also typically includes sense amplifiers and input/output (I/O) circuitry for reading, writing, and erasing data to and from array **105**. In response to address signals A0-AN that are provided on address lines **130** during read, write, and erase operations, address buffers **135** control the operation of X gate decoder **115**, Y source/drain decoder **120**, and X source/drain decoder **125**. The address signals A0-AN are provided by a controller such as a microprocessor that is fabricated separately or together with memory **100**, or otherwise provided by any other suitable circuits. As described in detail below, the address signals A0-AN are decoded by X gate decoder **115**, Y source/drain decoder **120**, and X source/drain decoder **125** to perform reading, writing, and erasing operations on memory cells that include a

number of vertical floating gate field-effect transistors (FETs) formed on the sides of a semiconductor pillar on a substrate.

FIG. 2 is a schematic diagram illustrating generally one embodiment of array 105 in more detail. In FIG. 2, each memory cell 205 comprises two floating gate transistors 200, e.g. two field-effect transistors (FETs), each having an electrically isolated (floating) gate that controls electrical conduction between source and drain regions. The floating gate transistors 200 are arranged in cells 205, such as cells 205AA, 205BA, . . . , 205AN, in a first direction, e.g. in the Y-direction of the first source/drain interconnection lines YS1, YS2, . . . , YSN, and in cells such as 205AA, 205AB, . . . , 205AN in a second direction, e.g. in the X-direction of the data lines, XD1, XD2, . . . , XDN. In the embodiment of FIG. 2, each cell 205 includes two floating gate transistors 200 that share a common first source/drain region, such as a source region coupled to one of the first source/drain interconnection lines YS1, YS2, . . . , YSN. The floating gate transistors 200 of each cell 205 also share a common second source/drain region, such as a drain region coupled to one of the data lines, XD1, XD2, . . . , XDN. Each cell 205 has first and second source/drain regions that are fabricated using a common semiconductor pillar on a substrate, as explained below.

FIG. 3A is a perspective view illustrating generally one embodiment of a portion of array 105, including portions of four cells 205 of floating gate transistors 200, such as illustrated in FIG. 2. In FIG. 3A, the substantially identical cells 205 are illustrated by way of example through cells 205AA, 205BA, 205AB, and 205BB. Each cell 205 includes a semiconductor pillar 300, initially of a first conductivity type such as P- silicon, fabricated upon a monolithic substrate 305. In one embodiment, substrate 305 is a bulk semiconductor, such as P- silicon. In another embodiment, a semiconductor-on-insulator (SOI) substrate 305 includes an insulating layer, such as silicon dioxide (SiO₂), as described below.

Each pillar 300 includes a first source/drain region of a second conductivity type, such as N+ silicon source region 310, formed proximally to a sub-micron dimensioned interface between pillar 300 and substrate 305. Each pillar 300 also includes a second source/drain region of the second conductivity type, such as N+ silicon drain region 315, that is distal to substrate 305, and separated from source region 310 by a first conductivity type region, such as P- body region 320.

Each pillar 300 provides a source region 310, a drain region 315, and a body region 320 for the two floating gate transistors 200 of a particular memory cell 205. The two floating gate transistors 200 of each memory cell 205 are located on opposing sides of the pillar 300 therein. In one embodiment, the physical dimensions of each pillar 300 and the doping of P- body region 320 are both sufficiently small to allow operation of the floating gate transistors 200 that is characteristic of fully depleted body transistors. First source/drain region interconnection line YS1 electrically interconnects the source region 310 of each pillar 300 of cells 205AA, 205BA, . . . , 205NA. In one embodiment, the first source/drain interconnection lines YS1, YS2, . . . , YSN, comprise a conductively doped semiconductor of the second conductivity type, such as N+ silicon, disposed at least partially within substrate 305. For example, dopants can be ion-implanted or diffused into substrate 305 to form the first source/drain interconnection lines YS1, YS2, . . . , YSN. In another embodiment, the first source/drain interconnection lines YS1, YS2, . . . , YSN are formed above substrate 305.

For example, a doped epitaxial semiconductor layer can be grown on substrate 305, from which first source/drain interconnection lines YS1, YS2, . . . , YSN are formed. Alternatively, an undoped epitaxial semiconductor layer can be grown on substrate 305, and dopants then introduced by ion-implantation or diffusion to obtain the first source/drain interconnection lines YS1, YS2, . . . , YSN of the desired conductivity.

Each pillar 300 is outwardly formed from substrate 305, and is illustrated in FIG. 3A as extending vertically upward from substrate 305. Each pillar 300 has a top region that is separated from substrate 305 by four surrounding side regions. A floating gate 325 is formed substantially adjacent to two opposing side surfaces of pillar 300, and separated therefrom by a gate dielectric 330, such that there are two floating gates 325 per pillar 300, though FIG. 3A omits some of the floating gates 325 for clarity of illustration. Each floating gate 325 has a corresponding substantially adjacent control gate 335, from which it is separated by an intergate dielectric 340. Except at the periphery of array 105, each control gate 335 is interposed between two approximately adjacent pillars 300 and shared by two floating gate transistors 200, each of these floating gate transistors 200 having portions in one of the two approximately adjacent pillars 300.

Also interposed between approximately adjacent pillars 300, except at the periphery of array 105, are gate lines XG1, XG2, . . . , XGN that are substantially parallel to each other. In this embodiment, gate lines XG1, XG2, . . . , XGN are illustrated as running in the X-direction, e.g. parallel to data lines XD1, XD2, . . . , XDN, but gate lines XG1, XG2, . . . , XGN could also run in the Y direction, e.g. orthogonal to data lines XD1, XD2, . . . , XDN. Each of the gate lines XG1, XG2, . . . , XGN interconnects ones of the control gates 335. For example, gate line XG2 electrically interconnects control gates 335 of floating gate transistors 200, in which the control gates are shared between pairs of cells 205, e.g. 205AA and 205BA, 205AB and 205BB, . . . , 205AN and 205BN. In the embodiment of FIG. 3A, the gate lines XG1, XG2, . . . , XGN are disposed above substrate 305, as described below.

Drain regions 315 of the pillars 300 are interconnected by data lines XD1, XD2, . . . , XDN that are substantially parallel to each other in the X-direction, e.g. parallel to gate lines XG1, XG2, . . . , XGN, but data lines XD1, XD2, . . . , XDN could also run in the Y direction, e.g. orthogonal to gate lines XG1, XG2, . . . , XGN. FIG. 3A illustrates, by way of example, data lines XD1 and XD2, which are shown schematically for clarity. However, it is understood that data lines XD1, XD2, . . . , XDN comprise metal or other interconnection lines that are isolated from the underlying topology, e.g. pillars 300, floating gates 325, control gates 335, and gate lines XG1, XG2, . . . , XGN, by an insulating layer through which contact holes are etched to access the drain regions 315 of the pillars 300.

FIG. 3B is a cross-sectional view illustrating generally one embodiment of the invention looking in the X-direction, e.g. parallel to data lines XD1, XD2, . . . , XDN and gate lines XG1, XG2, . . . , XGN, which run perpendicularly to the plane of the illustration of FIG. 3B. FIG. 3B illustrates a row of cells 205, e.g. 205AA, 205BA, . . . , 205NA, having source regions 310 interconnected by one of first source/drain interconnection lines YS1, YS2, . . . , YSN, e.g. first source/drain interconnection line YS1, formed in substrate 305.

FIG. 4 is a plan view, looking toward the working surface of substrate 305, illustrating generally by way of example

one embodiment of one of cells **205** having two floating gate transistors **200**, such as cell **205BB**. In FIG. 4, each of the two floating gates **325** is adjacent to one of opposing sides of pillar **300**, and separated therefrom by gate dielectric **330**. Each control gate **335** is separated from a corresponding floating gate **325** by an intergate dielectric **340**. Each control gate **335** is integrally formed together with one of the gate lines **XG1, XG2, . . . , XGN**.

The center-to-center spacing ("pitch") between adjacent gate lines **XG1, XG2, . . . , XGN**, e.g. between **XG2** and **XG3**, is twice the minimum lithographic feature size **F**. Since two floating gate transistors **200** are contained within a cell **205** having an area of $4F^2$, an area of only $2F^2$ is needed per bit of data. In another embodiment, multiple charge states (more than two) are used to store more than one bit of data on a single floating gate transistor **200** in order to obtain correspondingly higher data storage densities. In one embodiment, four charge states are used to store two bits of data per floating gate transistor **200**, corresponding to four bits of data per memory cell **205**, such that an area of only F^2 is needed per bit of data. One example of using more than two charge states to store more than one bit of data per transistor is set forth an article by T. -S. Jung et al., entitled "A 117-mm² 3.3-V Only 128-Mb Multilevel NAND Flash Memory For Mass Storage Applications," *IEEE J. Solid-State Circuits*. Vol. 31, No. 11, November 1996. In a further embodiment, a continuum of charge states is used to store analog data in array **105**.

In one embodiment, programming of one of the floating gate transistors **200** is by hot electron injection. For example, a voltage of approximately 10 volts is provided, such as by X gate decoder **115**, through a particular one of gate lines **XG1, XG2, . . . , XGN** to a particular control gate **335**. A resulting inversion region (channel) is formed in the body region **320** at the surface that is approximately adjacent to the particular one of gate lines **XG1, XG2, . . . , XGN**. A voltage of approximately 5 Volts is provided, such as by X source/drain decoder **125**, through a particular one of data lines **XD1, XD2, . . . , XDN** to a particular drain region **315**. A voltage of approximately 0 Volts is provided, such as by Y source/drain decoder **120**, through a particular one of first source/drain interconnection lines **YS1, YS2, . . . , YSN**, to the particular source region **310** of the floating gate transistor **200**. Electrons are injected onto the floating gate **325** interposed between the control gate **335** and the pillar **300** in which the particular drain region **315** is disposed. The exact value of the voltages provided to the particular control gate **335** and drain region **315** will depend on the physical dimension of the floating gate transistor **200**, including the thickness of the gate dielectric **330**, the thickness of the intergate dielectric **340**, and the separation between source region **310** and drain region **315**. Alternatively, if higher voltages are provided to control gate **335**, and the gate dielectric **330** and intergate dielectric **340** are made thinner, the floating gate transistor **200** may be programmed instead by Fowler-Nordheim tunneling of electrons from the body region **320**, source region **310**, or drain region **315**.

In one embodiment, addressing a particular memory cell **205** for reading data includes selecting a particular one of data lines **XD1, XD2, . . . , XDN** and also selecting a particular one of first source/drain interconnection lines **YS1, YS2, . . . , YSN**. Addressing a particular floating gate transistor **200** within the particular memory cell **205** for reading data either includes selecting a particular one of gate lines **XG1, XG2, . . . , XGN**.

In one embodiment, reading data stored on a particular floating gate transistor **200** includes providing a voltage of

approximately 5 volts by X gate decoder **115** through a particular one of the gate lines **XG1, XG2, . . . , XGN** to the particular control gate **335** of the floating gate transistor **200**. A voltage of approximately 0 Volts is provided, such as by Y source/drain decoder **120**, through a particular one of first source/drain interconnection lines **YS1, YS2, . . . , YSN**, to the particular source region **310** of the particular floating gate transistor **200**. A particular one of data lines **XD1, XD2, . . . , XDN** that is switchably coupled to the drain region **315** of the floating gate transistor **200** is precharged to a positive voltage by a sense amplifier in X source/drain decoder **125**, then coupled to the drain region **315** to determine the conductivity state of the floating gate transistor **200** between its source region **310** and drain region **315**.

If there are no electrons stored on the floating gate **325**, the floating gate transistor **200** will conduct between its source region **310** and drain region **315**, decreasing the voltage of the particular one of data lines **XD1, XD2, . . . , XDN** toward that voltage of its source region **310**, e.g. toward a "low" binary logic level voltage of approximately 0 Volts. If there are electrons stored on the floating gate **325**, the floating gate transistor **200** will not conduct between its source region **310** and drain region **315**. As a result, the sense amplifier will tend to increase the voltage of the particular one of data lines **XD1, XD2, . . . , XDN** toward a positive voltage, e.g. toward a "high" binary logic voltage level.

In one embodiment, erasure of floating gate transistors **200** includes providing an erasure voltage difference of approximately between -10 and -12 Volts from a source region **310** to a corresponding control gate **335**. For example, a voltage of approximately 0 Volts is provided, such as by Y source/drain decoder **120**, to source regions **310** of floating gate transistors **200** that are interconnected by one or several first source/drain interconnection lines **YS1, YS2, . . . , YSN**. A voltage of approximately between -10 and -12 Volts is provided, such as by X gate decoder **115**, through a corresponding one or several of the gate lines **XG1, XG2, . . . , XGN** to the control gates **335** of the floating gate transistors **200** to be erased. As a result of the negative voltage applied to the control gates **335**, electrons are removed from the corresponding floating gates **325** by Fowler-Nordheim tunneling, thereby erasing the data from ones of the floating gate transistors **200**. In another example, a voltage of approximately between -5 and -6 Volts is applied to the control gates **335** and a voltage of approximately between +5 and +6 Volts is applied to the source regions **310** in order to obtain the erasure voltage difference of approximately between -10 and -12 Volts from a source region **310** to a corresponding control gate **335**. The exact value of the erasure voltage difference will vary depending upon the physical dimensions of the floating gate transistor **200** and the thicknesses of gate dielectric **330** and intergate dielectric **340**.

In one embodiment, the entire array **105** of floating gate transistors **200** is simultaneously erased by applying approximately between -10 and -12 Volts to each of gate lines **XG1, XG2, . . . , XGN**, and also applying 0 Volts to each of first source/drain interconnection lines **YS1, YS2, . . . , YSN**. In another embodiment, one or more sectors of array **105** are simultaneously erased by selectively applying approximately between -10 and -12 Volts to one or more of gate lines **XG1, XG2, . . . , XGN**, and also applying 0 Volts to one or more of first source/drain interconnection lines **YS1, YS2, . . . , YSN**.

FIGS. 5-13 illustrate generally one embodiment of a method of forming memory array **105**. In this embodiment,

the array **105** is formed using bulk silicon processing techniques and is described, by way of example, with respect to a particular technology having a minimum lithographic feature size F , which is also sometimes referred to as a critical dimension (CD), of 0.4 microns. However, the process steps described below can be scaled accordingly for other minimum feature sizes without departing from the scope of the invention.

In FIG. 5, a P- silicon starting material is used for substrate **305**. A first source/drain layer **500**, of approximate thickness between 0.2 microns and 0.5 microns, is formed at a working surface of substrate **305**. In one embodiment, first source/drain layer **500** is N+ silicon formed by ion-implantation of donor dopants into substrate **305**. In another embodiment, first source/drain layer **500** is N+ silicon formed by epitaxial growth of silicon upon substrate **305**. On the first source/drain layer **500**, a semiconductor epitaxial layer **505**, such as P- silicon of 0.6 micron approximate thickness, is formed, such as by epitaxial growth. A second source/drain layer **510**, such as N+ silicon of 150 nanometer approximate thickness, is formed at a surface of the epitaxial layer **505**, such as by ion-implantation of donor dopants into P- epitaxial layer **505** or by epitaxial growth of N+ silicon on P- epitaxial layer **505**. A thin layer of silicon dioxide (SiO_2), referred to as pad oxide **515**, is deposited on the second source/drain layer **510**. Pad oxide **515** has a thickness of approximately 10 nanometers. A layer of silicon nitride (Si_3N_4), referred to as pad nitride **520**, is deposited on the pad oxide **515**. Pad nitride **520** has a thickness of approximately 100 nanometers.

In the bulk silicon embodiment of FIG. 6, photoresist masking and selective etching techniques are used to form, in the first direction (e.g., the Y direction, which is perpendicular to the plane of the drawing of FIG. 6), a plurality of substantially parallel first troughs **600** that extend through the pad nitride **520**, pad oxide **515**, second source/drain layer **510**, the underlying portion of epitaxial layer **505**, first source/drain layer **500**, and at least partially into underlying P- silicon substrate **305**. The photoresist is then removed by conventional photoresist stripping techniques, and an insulator **605**, such as silicon dioxide deposited by chemical vapor deposition (CVD), is formed to fill first troughs **600**. The insulator **605** is planarized (e.g. exposing underlying portions of pad nitride **520**) such as by chemical mechanical polishing (CMP) or other suitable planarization technique. A masking layer **610** such as, for example, silicon nitride deposited by CVD and having an approximate thickness of 200 nanometers, is then formed on insulator **605** and elsewhere on the working surface of substrate **305**. A photoresist layer **615** is then formed on masking layer **610**.

FIG. 7 is a perspective view, illustrating the selective etching, in a second direction (X-direction) that is substantially orthogonal to the first direction (Y-direction), of a plurality of substantially parallel second troughs **700**, as described below. Forming second troughs **700** includes patterning photoresist layer **615**, selectively etching masking layer **610**, pad nitride **520**, and underlying pad oxide **515**, such that portions of silicon dioxide insulator **605** in the second troughs **700** are exposed, together with N+ silicon second source/drain layer **510**. A selective etch, which preferentially removes silicon but doesn't substantially remove silicon dioxide, is used to etch through the exposed portions of second source/drain layer **510**, the underlying portions of epitaxial layer **505**, and approximately 100 nanometers into the underlying portions of first source/drain layer **500**. Photoresist **615** is then removed by conventional photoresist stripping techniques, leaving the structure illustrated in FIG. 7.

FIG. 8 is a plan view illustrating the resulting pattern formed by the selective etching steps described with respect to FIG. 7, which result in the forming of recesses **800** in second troughs **700** between first troughs **600**.

FIG. 9 is a cross-sectional view looking in the direction of second troughs **700** (e.g. such that the X-direction is orthogonal to the plane of the illustration of FIG. 9), as indicated by the cut line 9—9 in FIG. 8. In FIG. 9, a thin oxidation barrier layer **900**, such as silicon nitride of approximate thickness of 20 nanometers, is conformally deposited by CVD to protect against the oxidation of sidewalls of second troughs **700**. Barrier layer **900** is anisotropically etched to expose bottom portions of second troughs **700**. A bottom insulation layer **905** is formed on the bottoms of second troughs **700**, such as silicon dioxide of approximate thickness of 100 nanometers formed by thermal oxidation of the exposed bottom portions of second troughs **700**.

In FIG. 10, barrier layer **900** is stripped from the sidewalls of the second troughs **700**, such as by a brief phosphoric acid etch, which is timed to expose the sidewalls of the second troughs **700** but which avoids significant removal of the thick silicon nitride masking layer **610**. A gate dielectric layer **1000**, such as silicon dioxide of thickness approximately between 5 nanometers and 10 nanometers (sometimes referred to as "tunnel oxide"), is formed substantially adjacent to the exposed sidewalls of the second troughs **700**. A conductive layer **1005**, such as N+ doped polysilicon, is formed in the second troughs **700**, such as by CVD, to fill the second troughs **700**. The conductive layer **1005** is planarized, such as by chemical mechanical polishing (CMP) or other suitable planarization technique.

In FIG. 11, the conductive layer **1005** is etched back in the second troughs **700** to approximately at or slightly above the level of the silicon surface, which is defined by the interface between the second source/drain layer **510** and the pad oxide **515** layer. A spacer layer, such as silicon nitride of an approximate thickness of 100 nanometers, is deposited by CVD and anisotropically etched by reactive ion etching (RIE) to leave nitride spacers **1100** along the sidewalls of the second troughs **700**, e.g. on the etched back portions of the conductive layer **1005**, on the portions of insulator **605** in the intersections of first troughs **600** and second troughs **700**, and against the second gate dielectric **1000**.

In the perspective view of FIG. 12, spacers **1100** are used as a mask for the anisotropic etching in the second troughs **700** of the etched back portions of polysilicon conductive layer **1005** and the portions of silicon dioxide insulator **605**. A selective etch, which preferentially removes silicon dioxide but doesn't substantially remove polysilicon, is used to etch into portions of silicon dioxide insulator **605**, but not the portions of polysilicon conductive layer **1005** in second troughs **700**. The portions of silicon dioxide insulator **605** in second troughs **700** are etched until they are approximately even with adjacent portions of bottom insulating layer **905**. Then, a selective etch, which preferentially removes polysilicon but doesn't substantially remove silicon dioxide, is used to etch through portions of conductive layer **1005** in second troughs until the bottom insulation layer **905** is exposed, thereby forming from the polysilicon conductive layer **1005** separate floating gates **325** along the sidewalls of the second troughs **700**.

In the perspective view of FIG. 13, which is orthogonal to the perspective view of FIG. 12, an intergate dielectric **1300** is formed in the second troughs **700**, such that the intergate dielectric **1300** has an approximate thickness between 7

nanometers and 15 nanometers. In one embodiment, formation of intergate dielectric **1300** is by thermal growth of silicon dioxide. In another embodiment, formation of intergate dielectric **1300** is by deposition of oxynitride by CVD. Control gates **335** are formed between opposing floating gates **325** in the second troughs **700** and separated therefrom by the intergate dielectric **1300**. The control gates **335** in second troughs **700** are formed together with the gate lines $XG1, XG2, \dots, XGN$ in second troughs **700** by a single deposition of N+ doped polysilicon that fills second troughs **700** and is planarized, such as by CMP down to the top level of silicon nitride masking layer **610**. Phosphoric acid is used to remove the remaining silicon nitride, such as spacers **1100**, masking layer **610**, and pad nitride **520**, leaving the structure illustrated in FIG. **13**. An insulator such as silicon dioxide is then deposited, and subsequent processing follows conventional techniques for forming contact holes, terminal metal, and inter level insulator steps to complete wiring of the cells **205** and other circuits of memory **100**.

Though FIGS. **5–13** illustrate generally one embodiment of forming the memory array **105** using bulk silicon processing techniques, in another embodiment a semiconductor-on-insulator (SOI) substrate is formed from substrate **305**. In one such embodiment, a P- silicon starting material is used for substrate **305**, and processing begins similarly to the bulk semiconductor embodiment described in FIG. **5**. However, after the first troughs **600** are formed in FIG. **6**, an oxidation barrier layer is formed on the sidewalls of the first troughs **600**. An isotropic chemical etch is used to fully undercut the semiconductor regions separating the first troughs **600**, and a subsequent oxidation step is used to fill in the evacuated regions formed by the undercutting. As a result, an insulator is formed on the bottoms of first troughs **600**, bars of SOI are formed between first troughs **600**, and the topography on the working surface of substrate **305** is separated from substrate **305** by an insulating layer. The barrier layer is then removed from the sidewalls of first troughs **600**, which are then filled with insulator **605**, as illustrated in FIG. **6**. Thus, in the above described Figures, substrate **305** is understood to include bulk semiconductor as well as SOI embodiments in which the semiconductor integrated circuits formed on the surface of substrate **305** are isolated from each other and an underlying semiconductor portion of substrate **305** by an insulating layer.

One such method of forming bars of SOI is described in the Noble U.S. patent application Ser. No. 08/745,708 which is assigned to the assignee of the present application and which is herein incorporated by reference. Another such method of forming regions of SOI is described in the Forbes U.S. patent application Ser. No. 08/706,230, which is assigned to the assignee of the present application and which is herein incorporated by reference.

Thus, the present invention provides a high density flash EEPROM having increased nonvolatile storage capacity. If a floating gate transistor **200** is used to store a single bit of data, an area of only $2F^2$ is needed per bit of data. If multiple charge states (more than two) are used, even less area is needed per bit of data, e.g. an area of F^2 is needed per bit of data when four charge states are used. The increased storage capacity of the high density flash EEPROM is particularly advantageous in replacing hard disk drive data storage in computer systems. In such an application, the delicate mechanical components included in the hard disk drive are replaced by rugged, small, and durable solid-state high density flash EEPROM packages. The high density flash EEPROMs provide improved performance, extended rewrite cycles, increased reliability, lower power consumption, and improved portability.

It is to be understood that the above description is intended to be illustrative, and not restrictive. Many other embodiments will be apparent to those of skill in the art upon reviewing the above description. For example, though the memory cells **205** have been described with respect to a particular embodiment having two floating gate transistors **200** per pillar **300**, a different number of floating gate transistors per pillar could also be used. It is also understood that the above structures and methods, which have been described with respect to EEPROM memory devices having floating gate transistors **200**, are also applicable to dynamic random access memories (DRAMs) or other integrated circuits using vertically oriented field-effect transistors that do not have floating gates. Thus, the scope of the invention is not limited to the particular embodiments shown and described herein.

What is claimed is:

1. A method of forming a memory array, the method comprising the steps of:

forming a plurality of first conductivity type semiconductor pillars upon a substrate, each pillar having top and side surfaces;

forming a plurality of first source/drain regions, of a second conductivity type, each of the first source/drain regions formed proximally to an interface between a pillar and the substrate;

forming a plurality of second source/drain regions, of a second conductivity type, each of the second source/drain regions formed within one of the pillars and distal to the substrate and separate from the first/source drain/region;

forming a gate dielectric on at least a portion of the side surface of the pillars;

forming a plurality of floating gates, each of the floating gates formed substantially adjacent to a portion of the side surface of one of the pillars and separated therefrom by the gate dielectric;

forming a plurality of control gates, each of the control gates formed substantially adjacent to one of the floating gates and insulated therefrom;

forming an intergate dielectric, interposed between ones of the floating gates and one of the control gates;

forming a plurality of gate lines that interconnect one of the control gates;

forming at least one first source/drain interconnection line interconnecting one of the first source/drain regions; and

forming a plurality of data lines, each data line interconnecting one of the second source drain/regions.

2. The method of claim **1**, further comprising the step of forming an insulating layer between the semiconductor pillars and a semiconductor portion of the substrate.

3. The method of claim **1**, wherein the step of forming the at least one first source/drain interconnection line is carried out at least partially within the substrate.

4. The method of claim **1**, wherein the step of forming the plurality of gate lines includes forming a plurality of substantially parallel gate lines.

5. The method of claim **1**, wherein the step of forming the plurality of pillars further comprises the steps of:

growing an epitaxial layer on the substrate;

etching the epitaxial layer and a portion of the substrate to form a plurality of first troughs therein for carrying an insulator; and

etching the epitaxial layer to form therein a plurality of second troughs, substantially orthogonal to the plurality of first troughs, the second troughs for carrying the gate lines.

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6. The method of claim 5, wherein the step of forming the plurality of floating gates comprises the steps of:
 depositing polysilicon in the second troughs; and
 etching the deposited polysilicon in a median portion of the second troughs to form one of the floating gates on either side of the second troughs, each floating gate adjacent to one of the pillars but separated therefrom by the gate dielectric.
7. The method of claim 6, wherein the steps of forming the plurality of gate lines comprises the steps of:
 etching into the substrate in a median portion of the second troughs; and
 depositing conductive polysilicon in and above the substrate in the etched median portion of the second troughs to form the gate lines and one of the control gates.
8. The method of claim 1, wherein the step of forming the plurality of second source/drain regions comprises the step of ion-implanting a dopant of the second conductivity type.
9. The method of claim 1, wherein the step of forming the gate dielectric comprises the step of growing on the side surface of each pillar a layer of silicon dioxide of thickness approximately between 5 nanometers and 10 nanometers.
10. The method of claim 1, wherein the step of forming the plurality of data lines comprises the steps of:
 depositing an insulator over the pillars, the floating and control gates, and first and second gate lines;
 forming contact holes in the insulator to contact the second/source drain regions of each pillar;
 depositing a conductive layer on the insulator and in the contact holes; and
 etching the conductive layer to form data lines.
11. A method of forming a memory array on a substrate, the method comprising the steps of:

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- forming a first source/drain layer at a surface of the substrate;
 forming a semiconductor epitaxial layer on the first source/drain layer;
 forming a second source/drain layer at a surface of the epitaxial layer;
 etching, in a direction, a plurality of substantially parallel first troughs in the epitaxial layer;
 forming an insulator in the first troughs;
 etching, in a second direction that is substantially orthogonal to the first direction, a plurality of substantially parallel second troughs in the epitaxial layer;
 forming a gate dielectric layer substantially adjacent to sidewall regions of the second troughs;
 forming a conductive layer in the second troughs;
 removing a portion of the conductive layer in the second troughs such that floating gate regions are formed along the sidewall regions therein and separated from the sidewall regions by the gate dielectric layer;
 forming an intergate dielectric layer on exposed portions of the floating gate regions in the second troughs; and
 forming control gate regions and gate lines between opposing floating gate regions in the second troughs and separated from the floating gate regions in the second troughs by the intergate dielectric layer.
12. The method of claim 11, wherein the substrate is a bulk semiconductor.
13. The method of claim 11, wherein the substrate includes a semiconductor-on-insulator portion.
14. The method of claim 11, further comprising forming an insulating layer undercutting semiconductor regions between the first troughs.

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